KS54AHCT 821/822
KS74AHCT

10-Bit Bus Interface Flip-Flops with 3-State Outputs

Preliminary Specifications

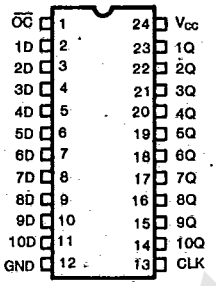
T-46-07-05

FEATURES

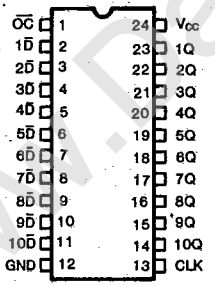
- **Functionally Equivalent to AMD's Am29821 and Am29822**
- **Provides Extra Data Width Necessary for Wider Address/Data Paths or Buses with Parity**
- **Power-Up-High-Impedance State**
- **Function, pin-out, speed and drive compatibility with 54/74ALS logic family**
- **Low power consumption characteristic of CMOS**
- **3-State outputs with high drive current (I_{OL} = 24 mA @ V_{OL} = 0.5V) for direct bus interface**
- **Inputs and outputs interface directly with TTL, NMOS and CMOS devices**
- **Wide operating voltage range: 4.5V to 5.5V**
- **Characterized for operation over industrial and military temperature ranges:**
  KS74AHCT: −40°C to +85°C
  KS54AHCT: −55°C to +125°C
- **Package options include plastic "small outline" packages, standard plastic and ceramic 300-mil DIPs**

PIN CONFIGURATIONS

'821



'822



DESCRIPTION

These 10-bit bus-interface flip-flops feature three-state outputs designed specifically for driving highly-capacitive or relatively low-impedance loads. They are suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

All of the flip-flops are edge-triggered and D-type. On the positive transition of the clock the Q outputs on the '821 will be true, and on the '822 will be complementary to the data input.

A buffered output-control input can be used to place the ten outputs in either a normal logic state (high or low levels) or a high-impedance state. The high-impedance state and increased drive provide the capability to drive the bus lines in a bus-organized system without need for interface or pull-up components. The output control ($\overline{OC}$) does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

These devices provide speeds and drive capability equivalent to their ALSTTL counterparts and yet maintain CMOS power levels. The input and output voltage levels allow direct interface with TTL, NMOS and CMOS devices without any external components.

All inputs and outputs are protected from damage due to static discharge by internal diode clamps to V_{CC} and ground.

FUNCTION TABLES

(Each Flip-Flop)
'821

Inputs			Output
$\overline{OC}$	CLK	D	Q
L	↑	H	H
L	↑	L	L
L	L	X	Q_0
L	H	X	Q_0
H	X	X	Z

'822

Inputs			Output
$\overline{OC}$	CLK	$\overline{D}$	Q
L	↑	H	L
L	↑	L	H
L	L	X	Q_0
L	H	X	Q_0
H	X	X	Z

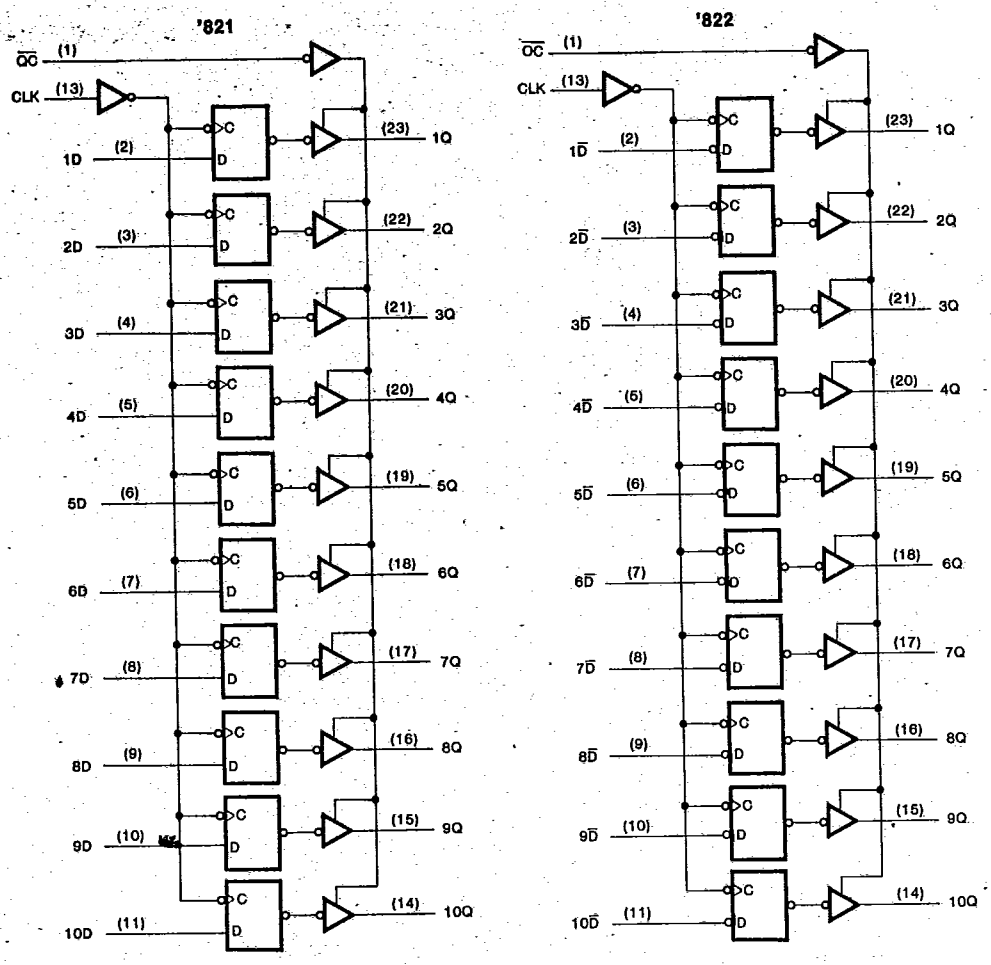
www.DataSheet4U.com

KS54AHCT KS74AHCT 821/822

10-Bit Bus Interface Flip-Flops with 3-State Outputs

T-46-07-05

LOGIC DIAGRAMS



KS54AHCT KS74AHCT 821/822

10-Bit Bus Interface Flip-Flops with 3-State Outputs

T-46-07-05

Absolute Maximum Ratings*

Supply Voltage Range V_{CC} . . . . . −0.5V to +7V
DC Input Diode Current, I_{IK}
($V_I < -0.5V$ or $V_I > V_{CC} + 0.5V$) . . . . . ±20 mA
DC Output Diode Current, I_{OK}
($V_O < -0.5V$ or $V_O > V_{CC} + 0.5V$) . . . . ±20 mA
Continuous Output Current Per Pin, I_O
($-0.5V < V_O < V_{CC} + 0.5V$) . . . . . ±70 mA
Continuous Current Through
V_{CC} or GND pins . . . . . ±250 mA
Storage Temperature Range, T_{stg} . . . −65°C to +150°C
Power Dissipation Per Package, P_d† . . . . . 500 mW

* Absolute Maximum Ratings are those values beyond which permanent damage to the device may occur. These are stress ratings only and functional operation of the device at or beyond them is not implied. Long exposure to these conditions may affect device reliability.

† Power Dissipation temperature derating:
Plastic Package (N): −12mW/°C from 65°C to 85°C
Ceramic Package (J): −12mW/°C from 100°C to 125°C

Recommended Operating Conditions

Supply Voltage, V_{CC} . . . . . 4.5V to 5.5V
DC Input & Output Voltages*, V_{IN}, V_{OUT} . . 0V to V_{CC}
Operating Temperature
Range KS74AHCT: −40°C to +85°C
KS54AHCT: −55°C to +125°C
Input Rise & Fall Times, t_r, t_f . . . . . Max 500 ns

* Unused inputs must always be tied to an appropriate logic voltage level (either V_{CC} or GND)

DC ELECTRICAL CHARACTERISTICS (V_{CC}=5V±10% Unless Otherwise Specified)

Characteristic	Symbol	Test Conditions	T_a = 25°C	KS74AHCT T_a = −40°C to +85°C	KS54AHCT T_a = −55°C to +125°C	Unit
			Typ	Guaranteed Limits		
Minimum High-Level Input Voltage	V_{IH}			2.0	2.0	2.0	V
Maximum Low-Level Input Voltage	V_{IL}			0.8	0.8	0.8	V
Minimum High-Level Output Voltage	V_{OH}	$V_{IN}=V_{IH}$ or V_{IL} $I_O=-20\mu A$ $I_O=-6mA$	V_{CC} 4.2	$V_{CC}-0.1$ 3.98	$V_{CC}-0.1$ 3.84	$V_{CC}-0.1$ 3.7	V
Maximum Low-Level Output Voltage	V_{OL}	$V_{IN}=V_{IH}$ or V_{IL} $I_O=20\mu A$ $I_O=12mA$ $I_O=24mA$	0	0.1 0.26 0.39	0.1 0.33 0.5	0.1 0.4	V
Maximum Input Current	I_{IN}	$V_{IN}=V_{CC}$ or GND		±0.1	±1.0	±1.0	μA
Maximum 3-State Leakage Current	I_{OZ}	Output Enable $=V_{IH}$ $V_{OUT}=V_{CC}$ or GND		±0.5	±5.0	±10.0	μA
Maximum Quiescent Supply Current	I_{CC}	$V_{IN}=V_{CC}$ or GND $I_{OUT}=0\mu A$		8.0	80.0	160.0	μA
Additional Worst Case Supply Current	ΔI_{CC}	per input pin $V_I=2.4V$ other inputs: at V_{CC} or GND $I_{OUT}=0\mu A$		2.7	2.9	3.0	mA

KS54AHCT KS74AHCT 821/822

10-Bit Bus Interface Flip-Flops with 3-State Outputs

T-46-07-05

AC ELECTRICAL CHARACTERISTICS (Input t_r, t_f<2 ns), AHCT821, AHCT822

Characteristic	Symbol	Conditions†	T_a=25°C V_{CC}=5.0V	KS74AHCT T_a=−40°C to +85°C V_{CC}=5.0V±10%		KS54AHCT T_a=−55°C to +125°C V_{CC}=5.0V±10%		Unit
			Typ	Min	Max	Min	Max	
Maximum Operating Frequency	f_{max}	C_L=50pF	50	35		30		MHz
Propagation Delay CLK to any Q	t_{PLH}	C_L=50pF	8		14		17	ns
		C_L=150pF	11		19		23	
	t_{PHL}	C_L=50pF	8		14		17	
		C_L=150pF	11		19		23	
Output Enable Time, $\overline{OC}$ to any Q	t_{PZL}	R_L=1kΩ, C_L=50pF	11		18		22	ns
		C_L=150pF	14		23		28	
	t_{PZL}	C_L=50pF	11		18		22	
		C_L=150pF	14		23		28	
Output Disable Time, $\overline{OC}$ to any Q	t_{PHZ}	R_L=1kΩ, C_L=50pF	13		18		22	ns
	t_{PLZ}		13		18		22	
Pulse Width, CLK High or Low	t_w		9	15		18		ns
Setup Time, Data before CLK↑	t_{su}		9	14		17		ns
Hold Time, Data after CLK↑	t_h		−3	0		0		ns
Input Capacitance	C_{IN}		5					pF
Output Capacitance	C_{OUT}	Output Disabled	10					pF
Power Dissipation Capacitance* (per stage)	C_{PD}	$\overline{OC}$=V_{CC}	5					pF
		$\overline{OC}$=GND	30					pF

* C_{PD} determines the no-load dynamic power dissipation: $P_D = C_{PD} V_{CC}^2 f + I_{CC} V_{CC}$.
† For AC switching test circuits and timing waveforms see section 2.

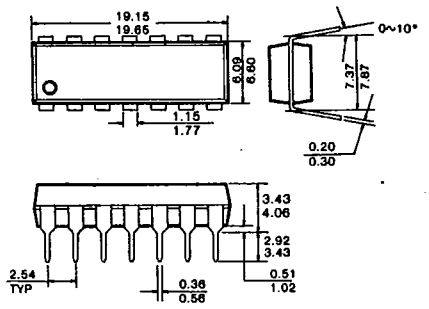
4

PACKAGE DIMENSIONS

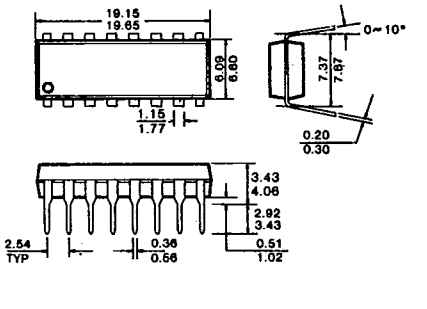
T-90-20

1. PLASTIC PACKAGES

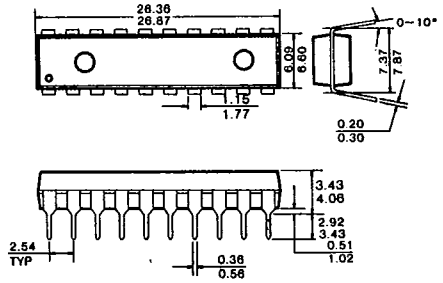
14-Pin Plastic DIP **Units: mm**



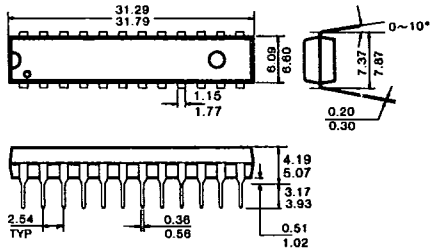
16-Pin Plastic DIP **Units: mm**



20-Pin Plastic DIP **Units: mm**



24-Pin Plastic DIP **Units: mm**



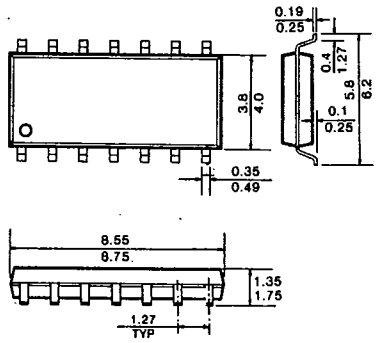
7

PACKAGE DIMENSIONS

T-90-20

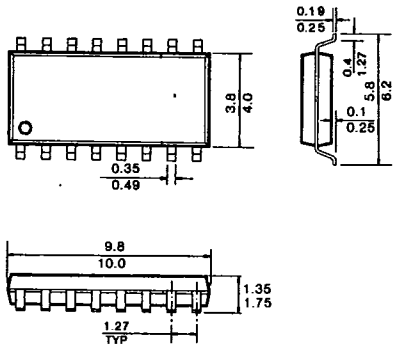
14-Pin SOP

Unit: mm



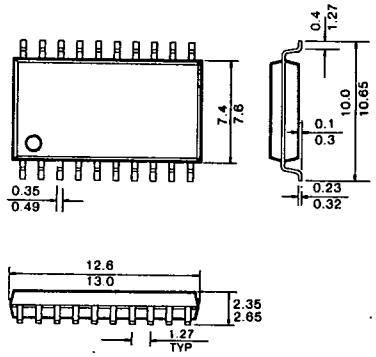
16-Pin SOP

Unit: mm



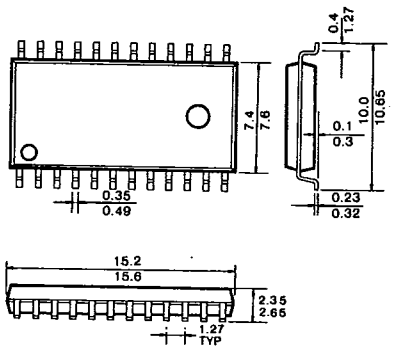
20-Pin SOP

Unit: mm



24-Pin SOP

Unit: mm

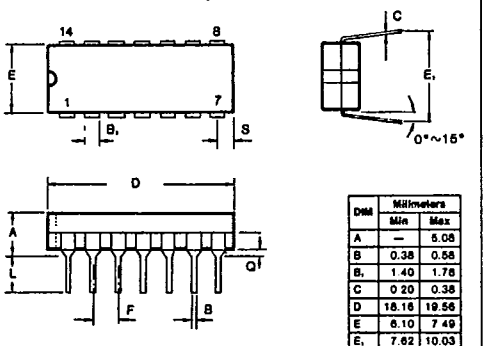


PACKAGE DIMENSIONS

T-90-20

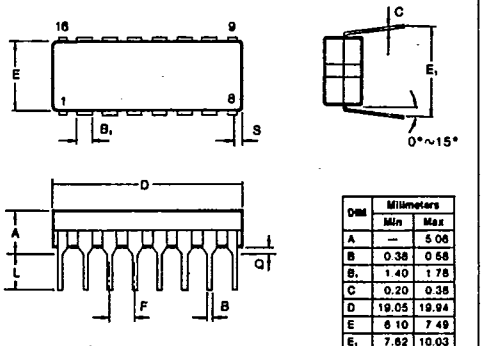
2. CERAMIC PACKAGES

14-Pin Ceramic DIP Units: mm



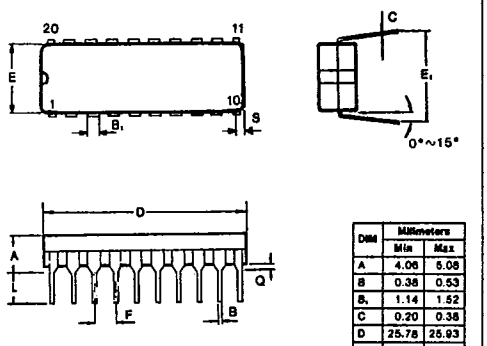
DIM	Millimeters	
	Min	Max
A	—	5.08
B	0.38	0.58
B1	1.40	1.78
C	0.20	0.38
D	18.16	19.56
E	6.10	7.49
E1	7.62	10.03
F	2.54	
L	3.16	4.19
Q	0.51	1.02
S	1.91	2.29

16-Pin Ceramic DIP Units: mm



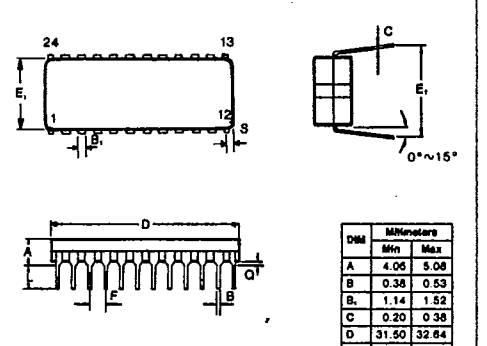
DIM	Millimeters	
	Min	Max
A	—	5.08
B	0.38	0.58
B1	1.40	1.78
C	0.20	0.38
D	19.05	19.94
E	6.10	7.49
E1	7.62	10.03
F	2.54	
L	3.16	4.19
Q	0.51	1.02
S	0.51	1.14

20-Pin Ceramic DIP Units: mm



DIM	Millimeters	
	Min	Max
A	4.06	5.08
B	0.38	0.53
B1	1.14	1.52
C	0.20	0.38
D	25.78	25.93
E	6.10	6.60
E1	7.77	7.98
F	2.54	
L	3.73	4.01
Q	0.38	0.89
S	0.51	1.14

24-Pin Ceramic DIP Units: mm



DIM	Millimeters	
	Min	Max
A	4.06	5.08
B	0.38	0.53
B1	1.14	1.52
C	0.20	0.38
D	31.50	32.64
E	7.24	7.75
E1	7.77	7.98
F	2.54	
L	3.73	4.01
Q	0.508	1.778
S	1.65	1.93

7